

### General Description

The MY013DNB is the high cell density  
 trenching N-CH MOSFET, which provides  
 excellent  $R_{DS(ON)}$  and efficiency for most of the  
 small power switching and load switch  
 applications.

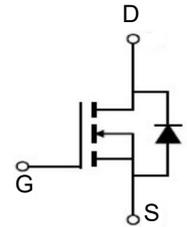
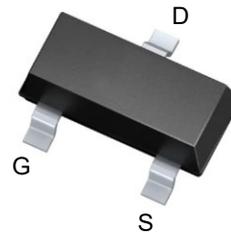


### Features

$V_{DSS}$	30	V
$I_D$	7.6	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	10	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	13	$m\Omega$

### Application

- Battery protection
- Load switch
- Power management



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY013DNB	SOT-23-3L	013DNB	3000

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-source Voltage	$V_{DS}$	30	V	
Gate-source Voltage	$V_{GS}$	$\pm 20$	V	
Drain Current	$I_D$	$T_A=25^\circ C$ @ Steady State	7.6	A
		$T_A=70^\circ C$ @ Steady State	5.5	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	30	A	
Total Power Dissipation @ $T_A=25^\circ C$	$P_D$	1.2	W	
Thermal Resistance Junction-to-Ambient @ Steady State <sup>B</sup>	$R_{\theta JA}$	104	$^\circ C/W$	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	$^\circ C$	

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	0.7	1.5	2.2	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.6A		10	13	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> =5.0A		13	15	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =5.6A,V <sub>GS</sub> =0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				5.6	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V,f=1MHZ		670		pF
Output Capacitance	C <sub>oss</sub>			92		
Reverse Transfer Capacitance	C <sub>rss</sub>			68		
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =15V,I <sub>D</sub> =5.6A		5.2		nC
Gate Source Charge	Q <sub>gs</sub>			0.9		
Gate Drain Charge	Q <sub>gd</sub>			1.3		
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =4.5V,V <sub>DD</sub> =15V, I <sub>D</sub> =1A, R <sub>GEN</sub> =2.8Ω		4.5		ns
Turn-on Rise Time	t <sub>r</sub>			2.5		
Turn-off Delay Time	t <sub>D(off)</sub>			14.5		
Turn-off Fall Time	t <sub>f</sub>			3.5		

A. Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Electrical and Thermal Characteristics

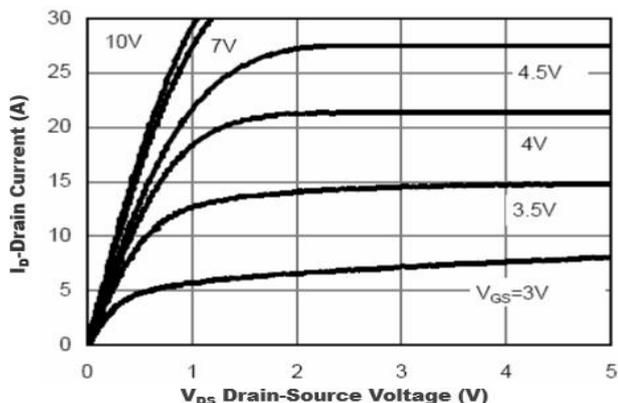


Figure1. Output Characteristics

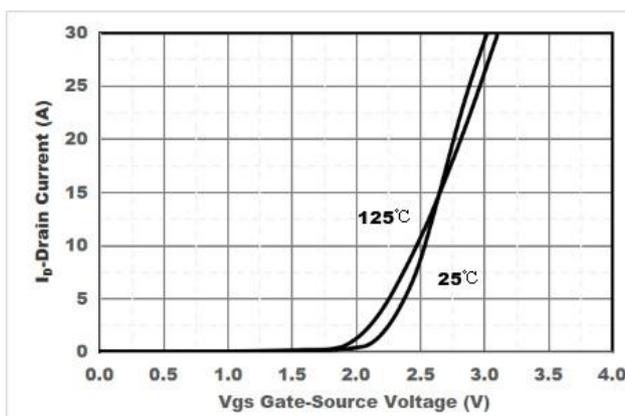


Figure2. Transfer Characteristics

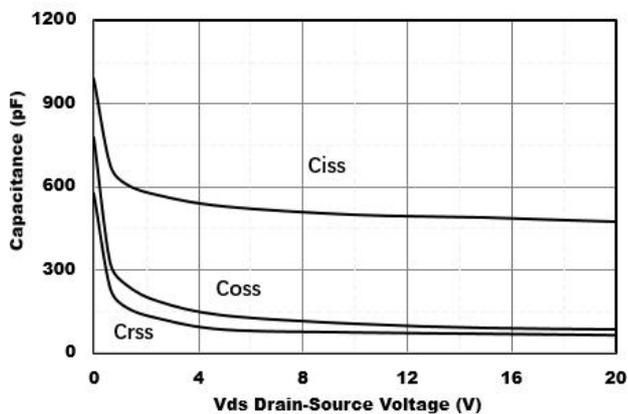


Figure3. Capacitance Characteristics

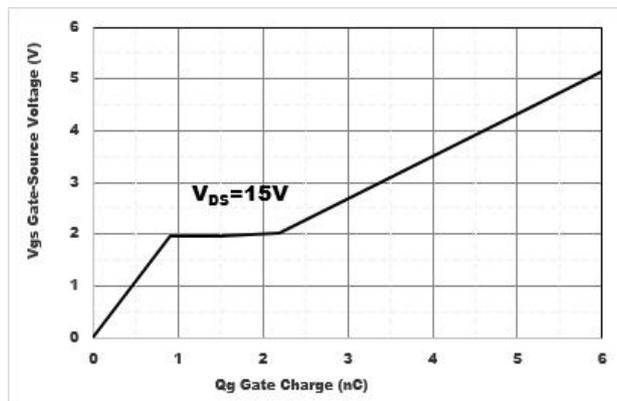


Figure4. Gate Charge

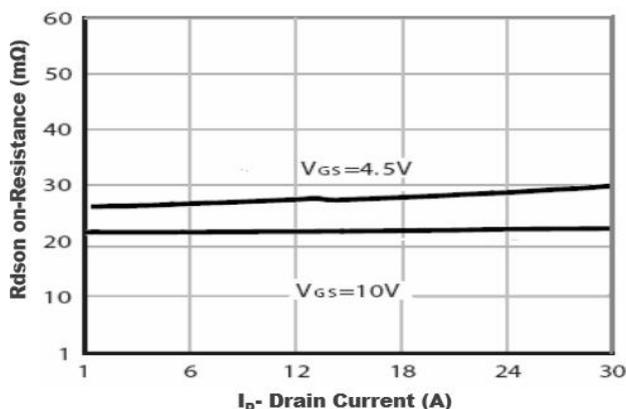


Figure5. Drain-Source on Resistance

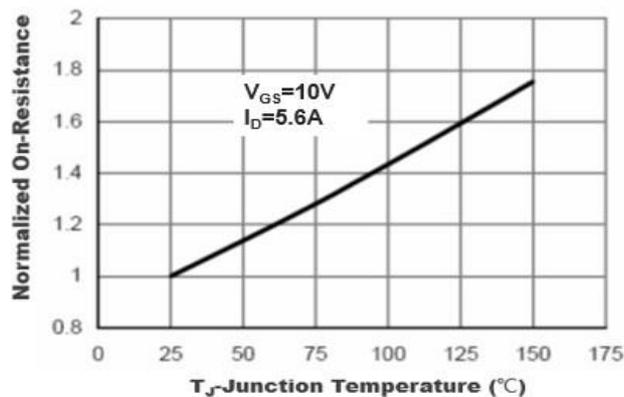


Figure6. Drain-Source on Resistance

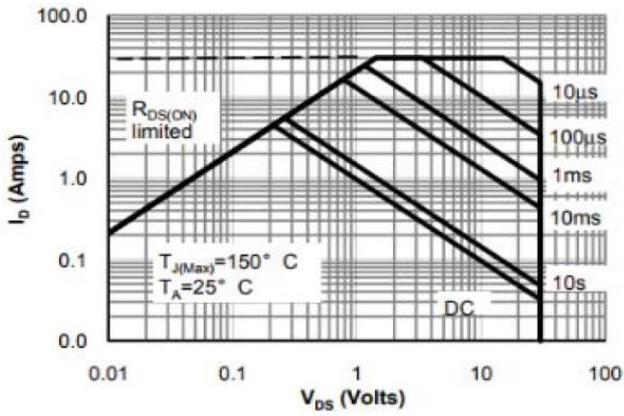


Figure7. Safe Operation Area

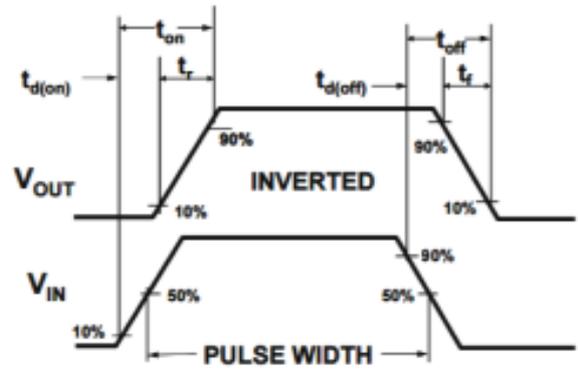
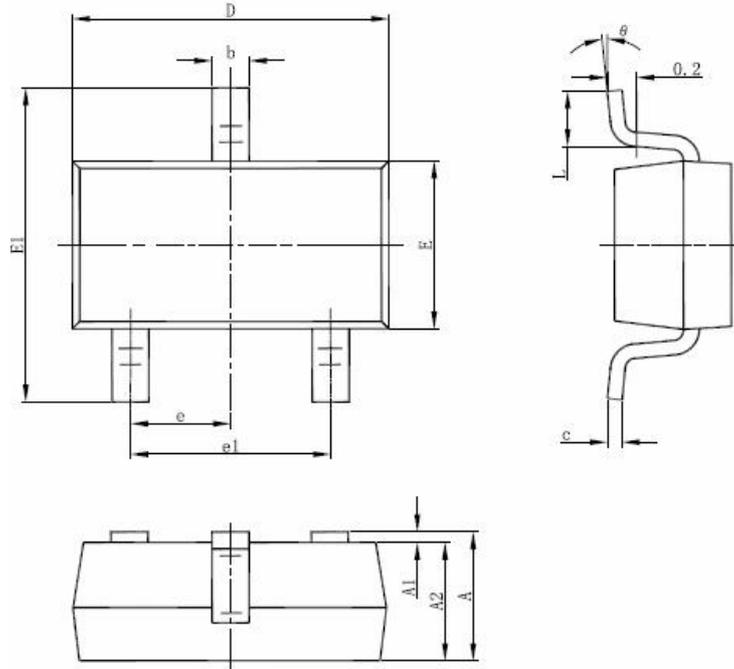


Figure8. Switching wave

Package Mechanical Data-SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°